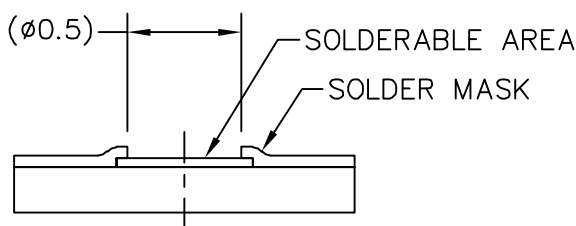
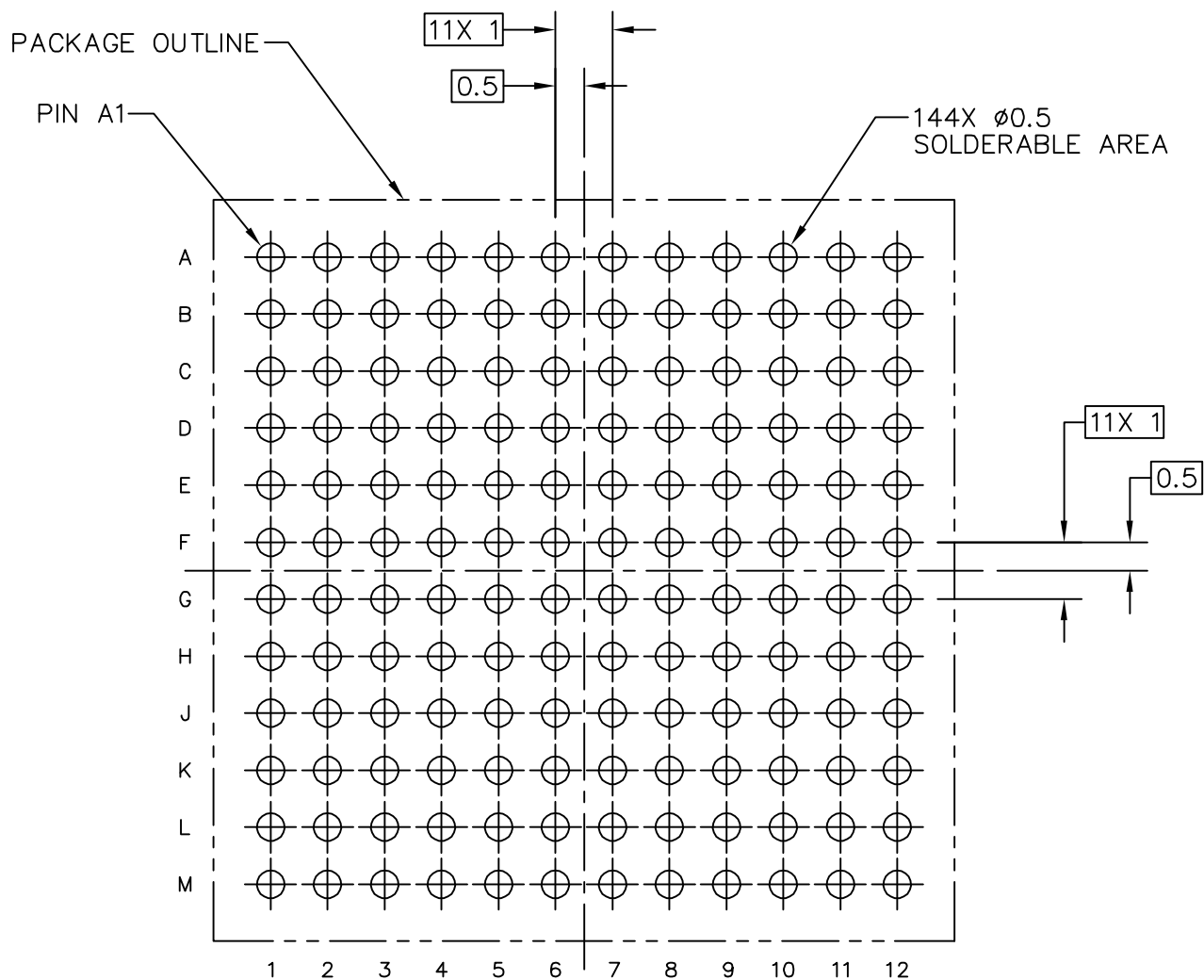
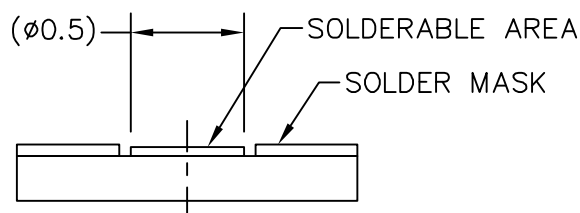


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TITLE: PBGA, LOW PROFILE, 144 I/O, 13 X 13 PKG, 1 MM PITCH (MAP)	DOCUMENT NO: 98ASA00222D	REV: A	
	CASE NUMBER: 2127-01	28 FEB 2011	
	STANDARD: NON-JEDEC		



PCB SMD PAD CONFIGURATION

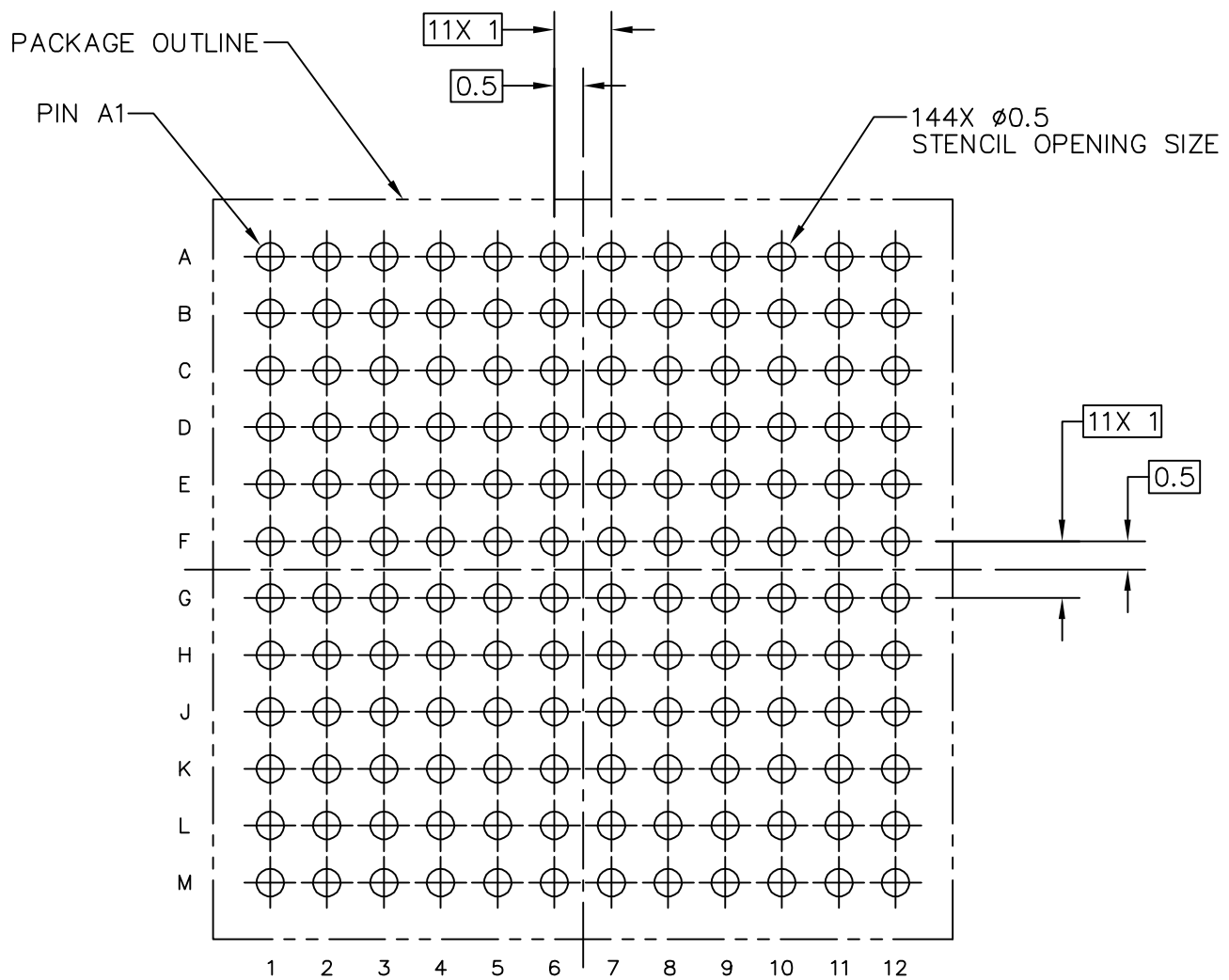


PCB NSMD PAD CONFIGURATION

PCB Cu GUIDELINES – SOLDERABLE AREAS

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. SHOWN IS AN EXAMPLE OF THE SOLDERABLE AREA, IT IS UP TO THE USER TO DETERMINE IF THE PCB PADS WILL BE SOLDER MASK DEFINED OR NON-SOLDER MASK DEFINED. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL / SPECIFIC REQUIREMENTS.

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SOLDER PASTE STENCIL DESIGN GUIDELINES

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL / SPECIFIC REQUIREMENTS.

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NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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